

# MA3X740 (MA740)

## Silicon epitaxial planar type

For super high speed switching

For small current rectification

### ■ Features

- Two MA3X721 (MA721) is contained in one package (series connection)
- Forward current (Average)  $I_{F(AV)} = 200$  mA (per single diode) rectification is possible

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	30	V
Repetitive peak reverse voltage	$V_{RRM}$	30	V
Forward current (Average)	Single	200	mA
	Series		
Peak forward current	Single	300	mA
	Series		
Non-repetitive peak forward surge current *	Single	1.0	A
	Series		
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

Note) \*: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

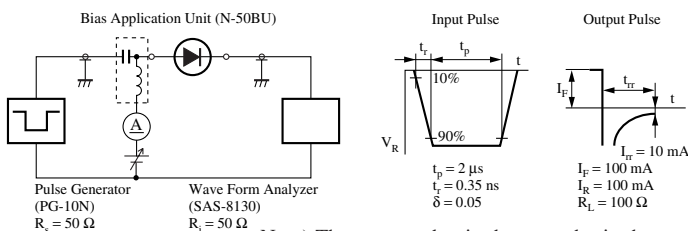
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 200$ mA			0.55	V
Reverse current	$I_R$	$V_R = 30$ V			50	$\mu\text{A}$
Terminal capacitance	$C_t$	$V_R = 0$ V, $f = 1$ MHz		30		pF
Reverse recovery time *	$t_{rr}$	$I_F = I_R = 100$ mA $I_{rr} = 10$ mA, $R_L = 100 \Omega$		3.0		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

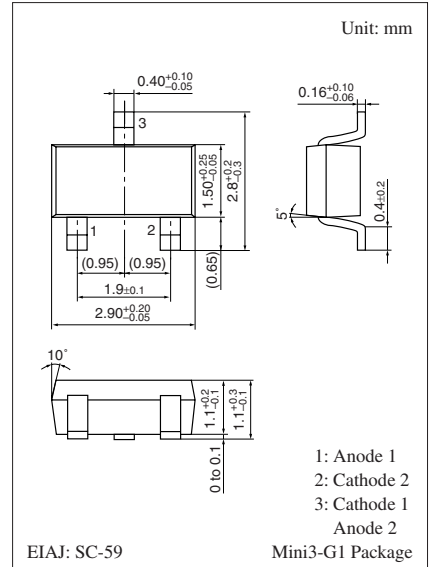
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 1 GHz.

4. \*:  $t_{rr}$  measurement circuit

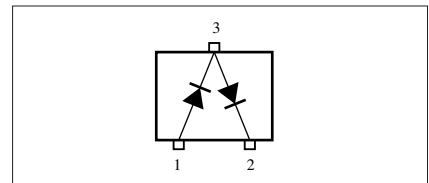


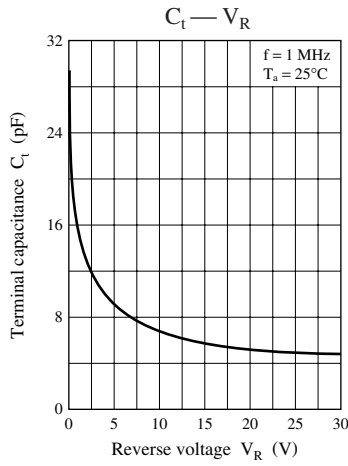
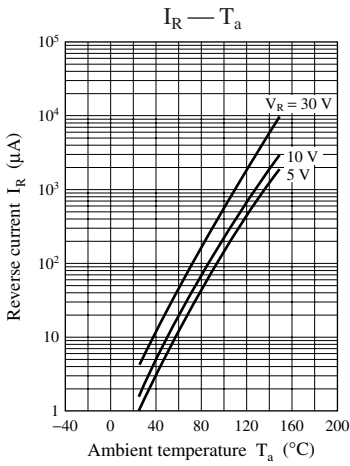
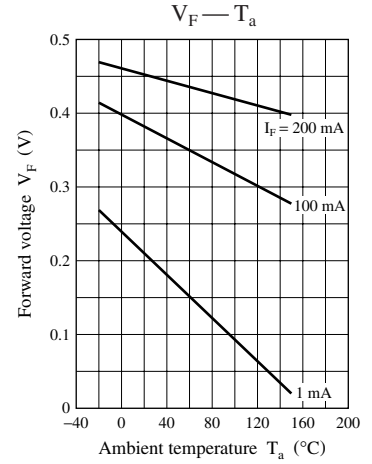
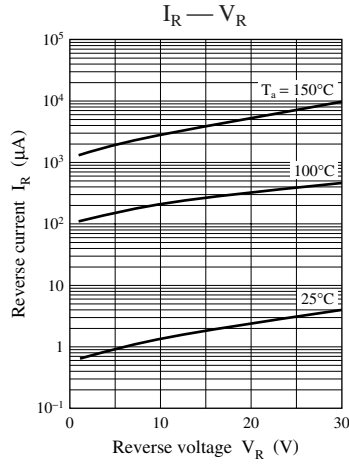
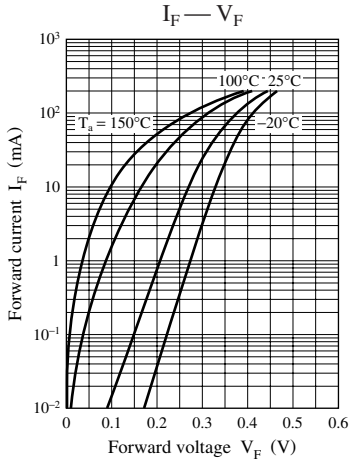
Note) The part number in the parenthesis shows conventional part number.



Marking Symbol: M3C

Internal Connection





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